| | Typ | L # | Hits | Search Text | DBs | Time Stamp |
|---|---|---|---|---|---|---|
| 1 | IS&R | L20 | 1370 | (257/690).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 11:11 |
| 2 | BRS | L17 | 6 | (die or dice or chip or chips or device or devices) near8 (input near3 bond$4 near3 pad$4) near8 (test$4 near3 pad$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 11:11 |
| 3 | IS&R | L19 | 1398 | (257/786).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 11:12 |
| 4 | BRS | L21 | 75 | 19 and (test$3 near2 pad$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 11:31 |
| 5 | BRS | L22 | 25 | 20 and (test$3 near2 pad$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 11:31 |

| | Type | L # | Hits | Search T xt | DBs | Time Stamp |
|---|---|---|---|---|---|---|
| 6 | IS&R | L23 | 479 | (257/620).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 12:08 |
| 7 | BRS | L24 | 2 | (die or dice or chip or chips or circuit$4) same active same (test$4 near2 pad$3) same (input near2 bond$4 near2 pad$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:06 |
| 8 | BRS | L25 | 176 | conduct$4 with (bond$4 near2 pad$4) with (test$4 near2 pad$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 13:59 |
| 9 | IS&R | L26 | 1 | ("6522018").PN. | USPAT | 2003/08/05 14:22 |
| 10 | BRS | L27 | 1 | "input bond pad" with "test pad" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:23 |
| 11 | BRS | L28 | 64 | "bond pad" with "test pad" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/08/05 14:24 |